



Material Content Data Sheet



Sales Product Name	SAK-TC233SP-32F200N AC			Issued		4. July 2019		
MA#	MA005348442							
Package	PG-TQFP-100-23			Weight*		698.65 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	23.351	3.34	3.34	33423	33423
leadframe	inorganic material	phosphorus	7723-14-0	0.056	0.01		80	
	non noble metal	zinc	7440-66-6	0.223	0.03		319	
	non noble metal	iron	7439-89-6	4.458	0.64		6381	
	non noble metal	copper	7440-50-8	181.029	25.91	26.59	259112	265892
wires	noble metal	gold	7440-57-5	0.002	0.00		2	
	noble metal	palladium	7440-05-3	0.033	0.00		47	
	non noble metal	copper	7440-50-8	1.466	0.21	0.21	2098	2147
encapsulation	organic material	carbon black	1333-86-4	1.408	0.20		2015	
	plastics	epoxy resin	-	59.588	8.53		85290	
	inorganic material	silicondioxide	60676-86-0	408.203	58.45	67.18	584270	671575
leadfinish	noble metal	palladium	7440-05-3	0.003	0.00		4	
	noble metal	silver	7440-22-4	0.003	0.00		4	
	noble metal	gold	7440-57-5	0.005	0.00		7	
	non noble metal	nickel	7440-02-0	4.642	0.66	0.66	6645	6660
plating	noble metal	silver	7440-22-4	0.005	0.00		7	
	noble metal	palladium	7440-05-3	0.005	0.00		8	
	noble metal	gold	7440-57-5	0.009	0.00		12	
	non noble metal	nickel	7440-02-0	8.662	1.24	1.24	12399	12426
glue	plastics	epoxy resin	-	1.211	0.17		1733	
	noble metal	silver	7440-22-4	4.292	0.61	0.78	6144	7877
*deviation	< 10%	Sum in total:			100.00			1000000

Important Remarks:

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This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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